

## pSEMI MATERIAL DECLARATION FORM

<b>Product:</b>	PE43620
<b>Ordering Codes:</b>	PE43620A-Z
<b>Description:</b>	UltraCMOS® 50 Ω RF Digital Attenuator 2-bit, 0, 6, 12, and 18 dB
<b>Package:</b>	12L 3x3 QFN
<b>Environmental Compliance</b>	EU RoHS Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
<b>Lead Finish</b>	NiPdAu
<b>Availability</b>	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	0.349885	5.11%	51,105.98
Die	Aluminum	7429-90-5	0.001064	0.02%	155.45
Die	Silicon	7440-21-3	0.000071	0.00%	10.36
Die	Arsenic	7440-38-2	0.000000	0.00%	0.05
Die	Boron	7440-42-8	0.000000	0.00%	0.05
Die	Phosphorus	7723-14-0	0.000001	0.00%	0.21
Die	Titanium	7440-32-6	0.000177	0.00%	25.91
Die	Tungsten	7440-33-7	0.003548	0.05%	518.18
Die	Cobalt	7440-48-4	0.000007	0.00%	1.04
Die	Copper	7440-50-8	0.000003	0.00%	0.41
Leadframe	Copper	7440-50-8	2.764500	40.38%	403,797.29
Leadframe	Iron	7439-89-6	0.066600	0.97%	9,727.94
Leadframe	Zinc	7440-66-6	0.003400	0.05%	496.62
Leadframe	Phosphorus	7723-14-0	0.000900	0.01%	131.46
Plating	Nickel	7440-02-0	0.026800	0.39%	3,914.55
Plating	Palladium	7440-05-3	0.002100	0.03%	306.74
Plating	Gold	7440-57-5	0.002100	0.03%	306.74
Die Attach	Silver	7440-22-4	0.050900	0.74%	7,434.72
Die Attach	Epoxy Resin	9003-36-5	0.012700	0.19%	1,855.03
Die Attach	t-Butyl phenyl glycidyl ether	3101-60-8	0.005300	0.08%	774.15
Die Attach	Phenolic hardener	92-88-6	0.001100	0.02%	160.67
Die Attach	Butyl cellosolve acetate	112-07-2	0.000700	0.01%	102.25
Wire	Gold	7440-57-5	0.080500	1.18%	11,758.25
Mold Compound	Silica Fused	60676-86-0	3.185500	46.53%	465,290.75
Mold Compound	Epoxy Resin	Trade secret	0.139000	2.03%	20,303.07
Mold Compound	Phenol Resin	Trade secret	0.139000	2.03%	20,303.07
Mold Compound	Carbon Black	1333-86-4	0.010400	0.15%	1,519.08
<b>Total Weight (mg)</b>			<b>6.846257</b>	100.00%	1,000,000